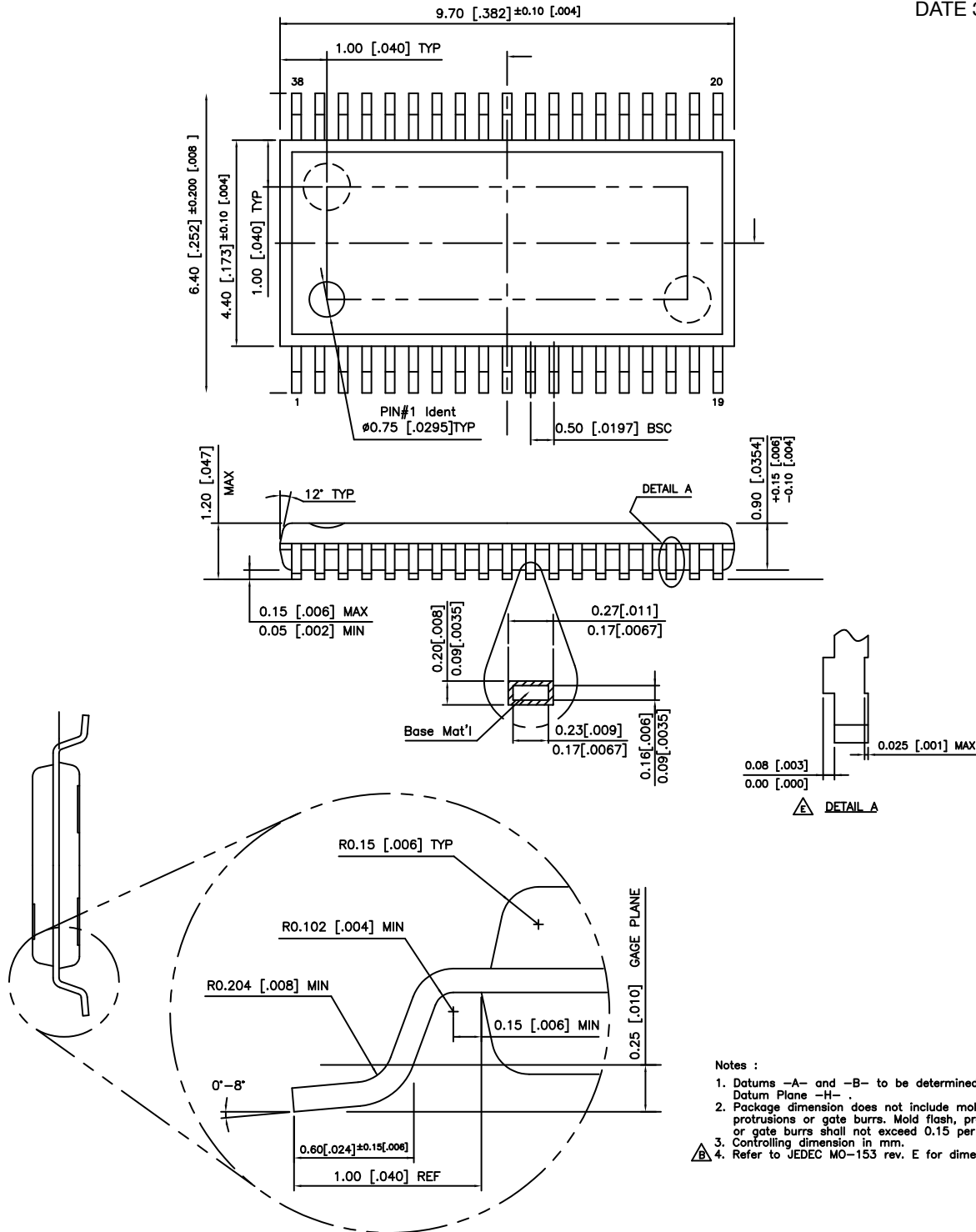


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Notes :

1. Datums --A-- and --B-- to be determined at Datum Plane --H--.
2. Package dimension does not include mold flash, protrusions or gate burrs. Mold flash, protrusions or gate burrs shall not exceed 0.15 per side.
3. Controlling dimension in mm.
4. Refer to JEDEC MO-153 rev. E for dimensions not shown.

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